

 Material Composition Declaration © Copyright 2005, IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1		IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x			Form Type * Distribute		Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information			
Supplier Information										
Company name* onsemi			Company unique ID		Unique ID Authority			Response Date* 2025-08-12		
Contact Name Product-Env-Stewards			Title - Contact Product Enviro Compliance		Phone - Contact* NA			Email - Contact* Product-Env-Stewards@onsemi.com		
Authorized Representative* Product-Env-Stewards			Title - Representative Product Enviro Compliance		Phone - Representative* NA			Email - Representative* Product-Env-Stewards@onsemi.com		
	Requester Item Number	Mfr Item Number	Mfr Item Name		Effective Date	Version	Manufacturing Site	Weight*	UOM	Unit Type
		STK544UC62K-E	3phase inverter HIC		2025-08-12		VN5	13900.0	mg	Each
Manufacturing Process Information										
	Terminal Plating / Grid Array Material	Terminal Base Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature		Max Time at Peak Temperature		Number of Reflow Cycles	
	Matte Tin (Sn) - annealed	CU Alloy	NA		0 C		30 seconds		3	
Comments										
For more information regarding material composition please refer to page 3										

RoHS Material Composition Declaration		Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).		
<p>Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a “RoHS restricted substance”) in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance in excess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier’s liability and the Company’s remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.</p>			
RoHS Declaration *	4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions		Supplier Acceptance * Accepted
Exemption: 7c-I Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound.			
Exemption List Version	EL-2011/534/EU		
Declaration Signature			
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.			
Supplier Digital Signature	Rastislav Drska		

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Ceramic Substrate	4678.99	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		58.4874	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		230.6742	mg
			B	Nickel (Ni)	7440-02-0		7.9543	mg
			Supplier	Acrylic resins	Proprietary Data		3.2753	mg
			Supplier	Copper (Cu)	7440-50-8		314.4281	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7		2.3395	mg
			Supplier	Aluminum (Al)	7429-90-5		4061.8313	mg
Chip Parts	49.8	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		0.0149	mg
			Supplier	Silver (Ag)	7440-22-4		2.1812	mg
			Supplier	Epoxy resins	129915-35-1		0.6076	mg
			Supplier	Bisphenol A, Epichlorohydrin polymer	25036-25-3, 25068-38-6		0.0299	mg
			Supplier	Tin (Sn)	7440-31-5		1.5787	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.3695	mg
			Supplier	Ceramic	12013-47-7, 12047-27-7		8.1074	mg
			Supplier	Phenolic resins	Proprietary Data		0.1444	mg
			Supplier	Palladium (Pd)	7440-05-3		0.0149	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		31.882	mg
			B	Nickel (Ni)	7440-02-0		2.4053	mg
			A	Lead Oxide (PbO)	1317-36-8	7c	0.1245	mg
			Supplier	Copper (Cu)	7440-50-8		1.3396	mg
Die	29.47	mg	Supplier	Silicon (Si)	7440-21-3		29.47	mg
Die Attach	1.56	mg	Supplier	Silver (Ag)	7440-22-4		1.2012	mg
			Supplier	Other Epoxy resins	Proprietary Data		0.2652	mg
			Supplier	Other Metal Oxide	Proprietary Data		0.0671	mg
			B	Antimony Pentoxide (Sb2O5)	1314-60-9		0.0265	mg
Lead Frame	788.87	mg	Supplier	Iron (Fe)	7439-89-6		0.71	mg
			Supplier	Copper (Cu)	7440-50-8		788.0023	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1578	mg
Mold Compound-Black	8247.03	mg		Brominated epoxy resin	proprietary data		164.9406	mg
			Supplier	Phenolic Resin	Proprietary Data		494.8218	mg

			Supplier	Epoxy Phenol Resin	Proprietary Data		164.9406	mg
			B	Antimony Trioxide (Sb2O3)	1309-64-4		247.4109	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		824.7031	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		577.2921	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		5772.9209	mg
Plating	16.97	mg	Supplier	Tin (Sn)	7440-31-5		8.8617	mg
			B	Nickel (Ni)	7440-02-0		8.1083	mg
Solder Ball	43.83	mg	Supplier	Silver (Ag)	7440-22-4		1.3587	mg
			Supplier	Tin (Sn)	7440-31-5		42.1469	mg
			B	Antimony (Sb)	7440-36-0		0.0044	mg
			Supplier	Copper (Cu)	7440-50-8		0.32	mg
Wire Bond	43.48	mg	Supplier	Silicon (Si)	7440-21-3		0.0043	mg
			Supplier	Aluminum (Al)	7429-90-5		43.4757	mg